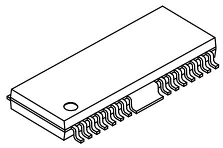
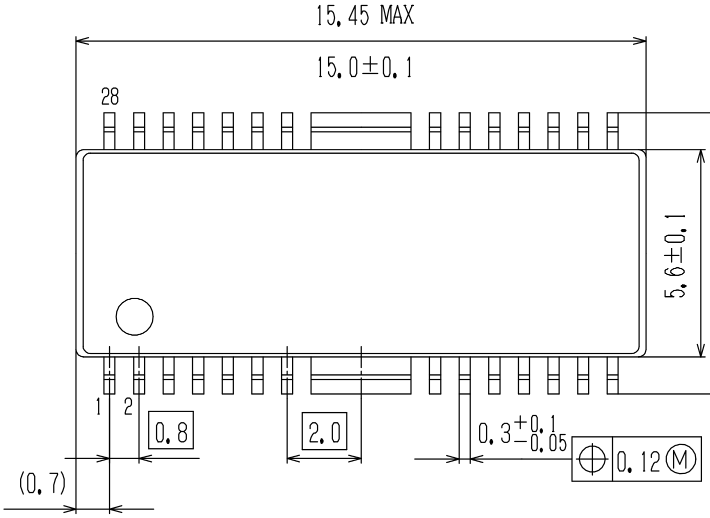
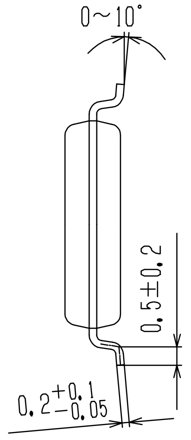
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

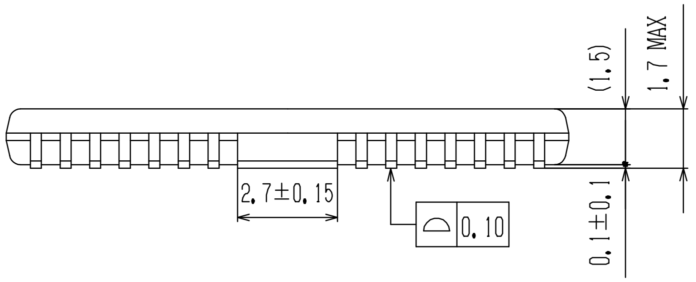


HSOP28 (275mil)
CASE 943AA
ISSUE A

DATE 31 OCT 2013

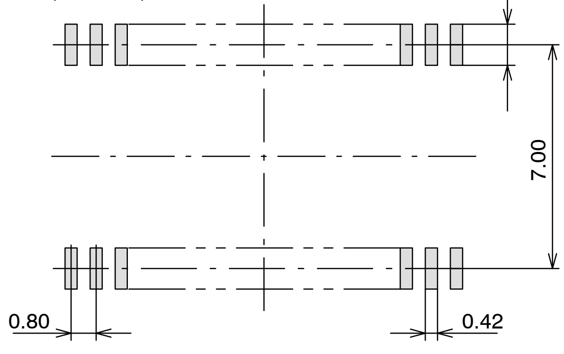






SOLDERING FOOTPRINT*

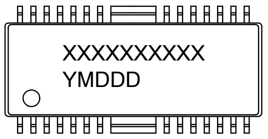
(Unit: mm)



NOTE: The measurements are not to guarantee but for reference only. Land pattern design in Fin area to be altered in response to customers' individual application.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪", may or may not be present.

DOCUMENT NUMBER:	**98AON65464E**	
STATUS:	**ON SEMICONDUCTOR STANDARD**	
NEW STANDARD:		
DESCRIPTION:	**HSOP28 (275 MIL)**	**PAGE 1 OF 2**

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ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION FROM SANYO ENACT# S−031 TO ON SEMICONDUCTOR. REQ. BY D. TRUHITTE.	30 NOV 2011
A	ADDED MARKING AND SOLDER FOOTPRINT INFORMATION. REQ. BY D. TRUHITTE	31 OCT 2013

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